

EXPRESS MAIL NO. EV415842357US

Docket No. 85A 3501
Date: February 5, 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Transmitted herewith for filing is the patent application for inventor(s):

YOSHIYUKI OGATA and HISASHI ARAI

For: DIE BONDING METHOD AND APPARATUS

Also enclosed are:

- ☒ 6 sheets of drawings
- ☒ Certified copy of Japanese Patent Application No. 2003-029183 of February 6, 2003 on which Convention priority is claimed
- ☒ Declaration and Power of Attorney
- ☒ Information Disclosure Statement by Applicant
- ☒ An assignment of the invention to KABUSHIKI KAISHA SHINKAWA

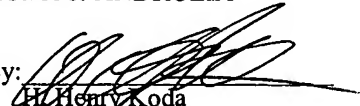
☒ Applicant claims Small Entity Status

CALCULATION OF FEES								
ITEM		TOTAL NO. OF CLAIMS		NO. OF CLAIMS OVER BASE	LG/SM \$ ENTITY FEE		\$ AMOUNT	\$ FEE
A	TOTAL CLAIMS FEE	4	-20	0	LG=\$18 SM=\$9	\$18	\$ 0	
B	INDEPENDENT CLAIMS FEE*	2	-3	0	LG=\$86 SM=\$43	\$86	\$ 0	
C	SUBTOTAL - ADDITIONAL CLAIMS FEE (ADD FINAL COLUMN IN LINES A + B)							\$ 0
D	MULTIPLE-DEPENDENT CLAIMS FEE					LARGE ENTITY FEE = \$290 SMALL ENTITY FEE = \$145		\$ 0
E	BASIC FEE					LARGE ENTITY FEE = \$770 SMALL ENTITY FEE = \$385		\$ 385
F	TOTAL FILING FEE (ADD TOTALS FOR LINES C, D, AND E)							\$ 385
G	ASSIGNMENT RECORDING FEE						\$ 40	\$ 40
	*LIST INDEPENDENT CLAIMS 1, 4							

- ☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Account No. 11-1445. A duplicate copy of this sheet is enclosed.
- ☒ A check in the amount of \$ 385 to cover the filing fee is enclosed.
- ☒ A check in the amount of \$ 40 to cover Assignment Recordation fee is enclosed.

Respectfully submitted,
KODA & ANDROLIA

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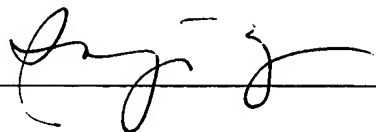
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on February 5, 2004 by Inja Yi.

Dated: 2/5/04

By: 

85A 3501

SHINKAWA

Applicant(s):

YOSHIYUKI OGATA and HISASHI ARAI

For:

DIE BONDING METHOD AND APPARATUS